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1 Scope

This specification shall be applied for back-electrode electret condenser microphone (Back-Electrode ECM).

2 Microphone model number

MIC-EMC6050PP-303

3 Electrical characteristics

Test Temperature: 15°C ~ 35°C

Test Room Humidity: 40% ~ 85 %R.H.

NO	Parameter	Condition	Limits			Unit
			Min	Nom	Max	
1	Directivity	Omnidirectional				
2	Sensitivity	1kHz(0dB=1V/Pa)	-33	-30	-27	dB
		1kHz(0dB=1V/ubar)	-53	-50	-47	dB
3	Output impedance	f=1kHz			2.2	kΩ
4	Current Consumption	VCC=4.5V, RL =2.2kΩ			0.5	mA
5	Operating Voltage		2.0	4.5	10	V
6	Total Harmonic Distortion	f=1kHz, Pin=94dB			1	%
7	S/N Ratio	f=1kHz, Pin=1Pa (A-Weighted curve)		60		dB
8	Acoustical Overload Point	<10% THD @1kHz			115	dB SPL

We use"Pascal (Pa)"indication of sensitivity as per the recommendation of I.E.C (International Electro technical Commission).The Sensitivity of “Pa”will increase 20dB comparing with “ubar” indication。Example: -60dB(0dB=1v/ubar)=-40dB(1v/Pa)

依 I.E.C.(国际电子协会) 建议，以"Pa"为灵敏度标示单位比"ubar"灵敏度标示单位增加 20dB

例如: -60dB(0dB=1V/ubar)=-40dB(1V/Pa)

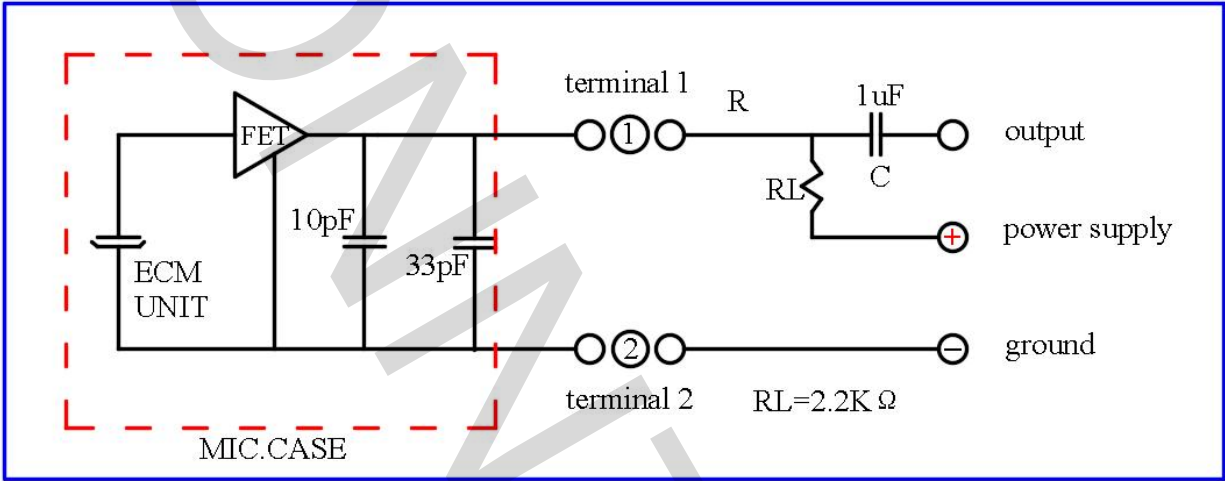
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Temperature conditions

Storage temperature: -20℃ ~ 70℃, With 40% ~ 85% R.H. humidity.

Operating temperature: -20℃ ~ 70℃, With 40% ~ 85% R.H. humidity.

4 Measurement circuit



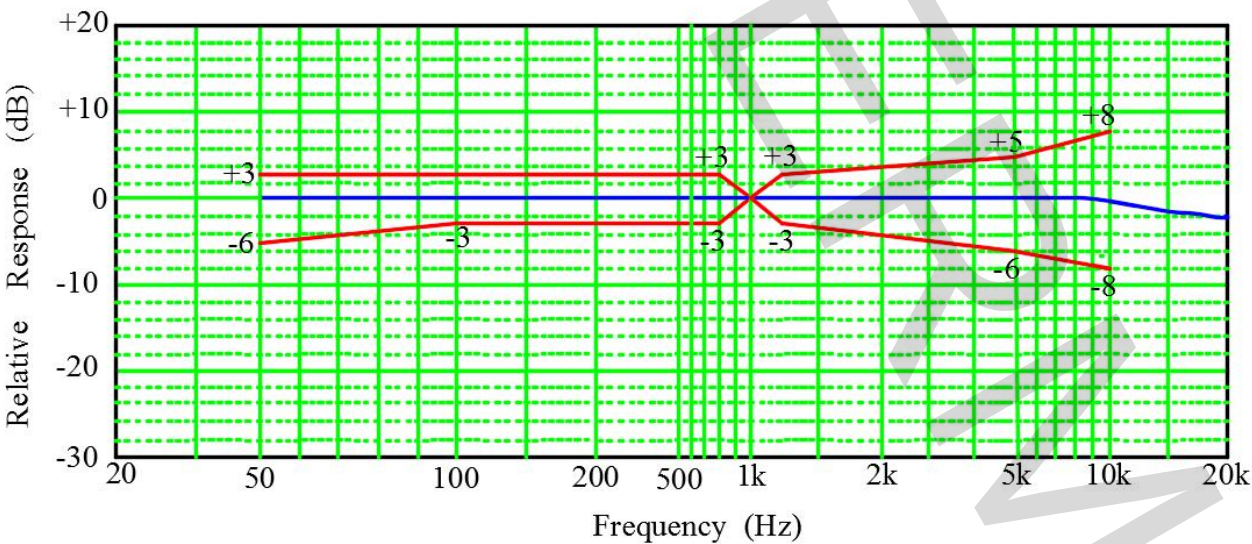
5 Typical frequency response curve

Test temperature: 15℃ ~ 35 ℃

Acoustic stimulus: 1Pa (94dB SPL at 1kHz) at 50cm from the loud-speaker.

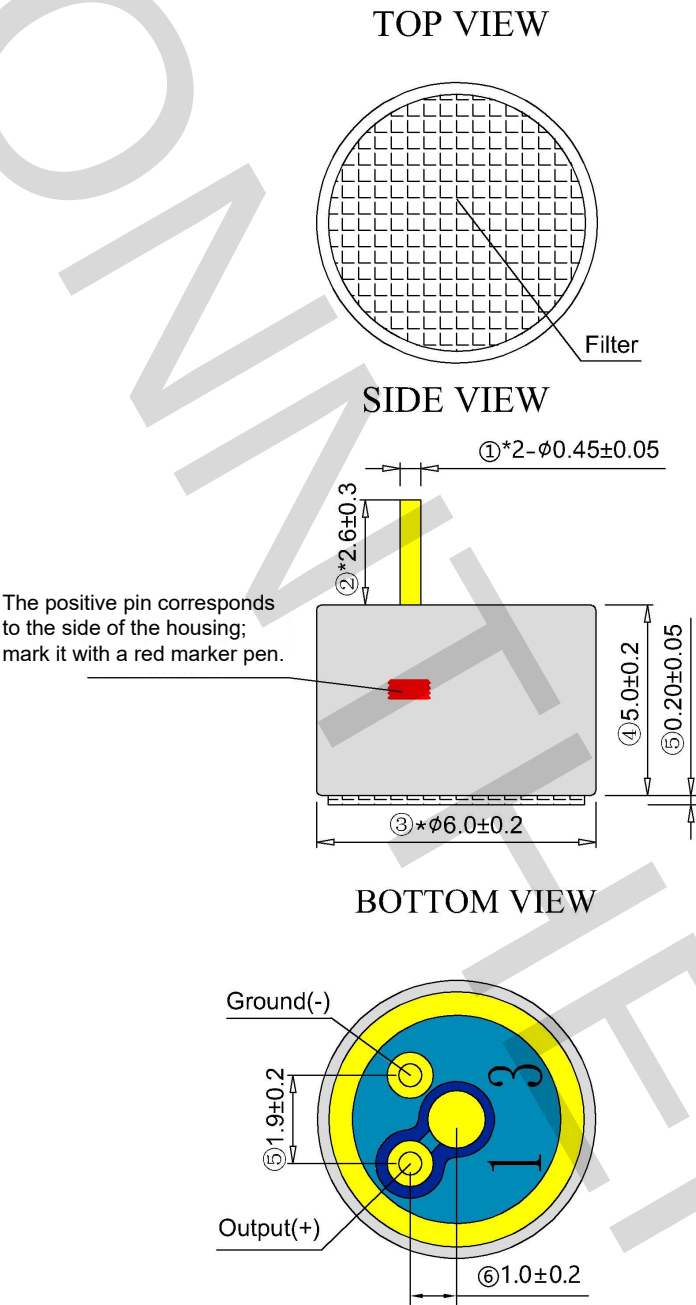
The loud-speaker must be calibrated to make a flat frequency response curve input signal.

Placement Location: The frequency response of microphone unit measured at 50cm from the loud-speaker.



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6 Microphone outline dimensions



Note:

All dimensions are in millimeter(mm).

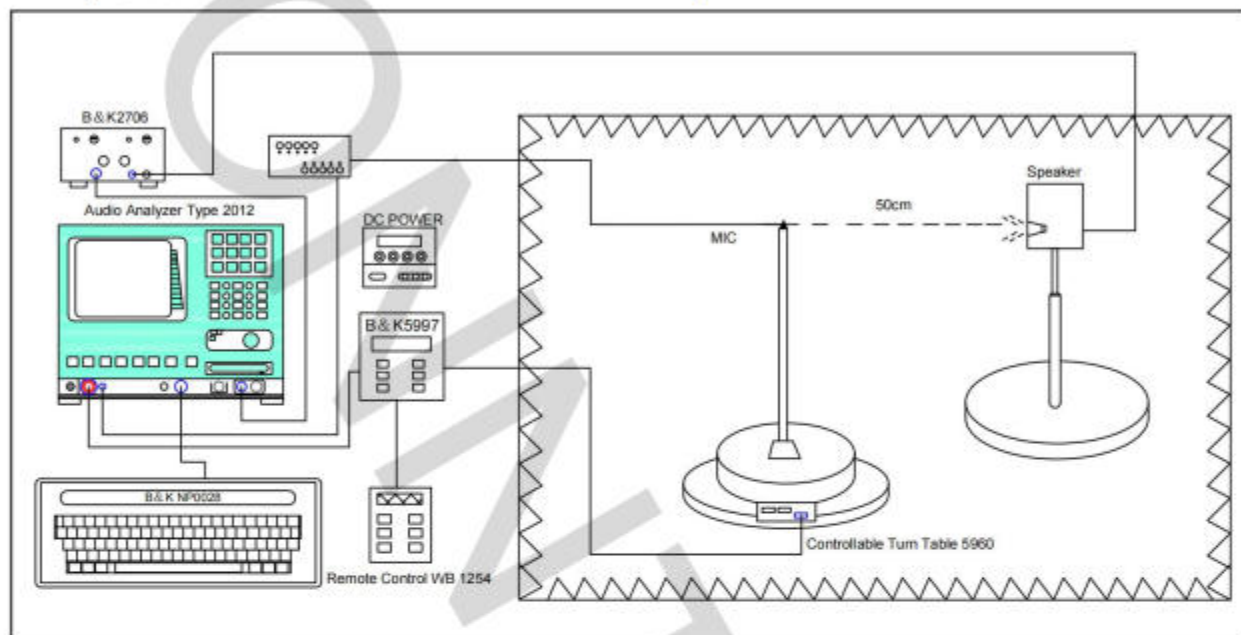
Tolerance: ± 0.1 mm unless otherwise specified.

The dimensions marked with * are the key controlled dimensions.

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7 Measurement system

The specification for the far-field measurement system conforms to IEC60268-4.



8 Reliability test

Sensitivity difference shall be within $\pm 3\text{dB}$ (at 1kHz) between before and after the experiment, Wait for 2 hours to test after completing experiment.

Ambient temperature: $15^{\circ}\text{C} \sim 35^{\circ}\text{C}$.

8.1 Drop Test

Height: 1m

Drop Face: 2cm hardwood board

Duration: 3 times in each of three directions in state of packing

8.2 Vibration Test

Frequency range: 10~55Hz

Accelerate: 3mm amplitude

Duration per axis: 30minutes vibration at three axes.

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8.3 High Temperature Test

Temperature: 80°C

Duration: 96 hours

8.4 Low Temperature Test

Temperature: -40°C

Duration: 96 hours

8.5 Temperature Cycle Test

Low temperature: -25±2°C X 30min ->

Normal temperature: 20°C±2°C X 10min ->

High temperature: 70°C±2°C X 30min ->

Normal temperature: 20°C±2°C X 10min)

No. of repetitions: 5

8.6 Humidity Test

Temperature: 70°C

Humidity: 90~95% R.H.

Duration: 96 hours

8.7 Soldering Heat Shock Test

Duration per axis: 30minutes vibration at three axes

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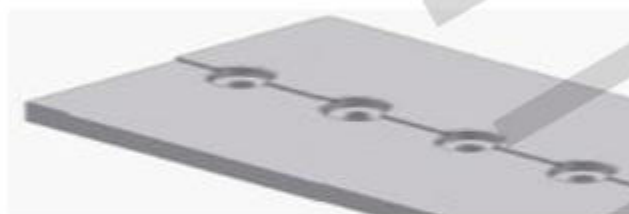
9 Regarding the soldering operation

9.1 Soldering Condition

Every ECM contains a FET with microphone body. This FET is easy to damageable from excessive heat and electrical shock. Proper attention for the soldering work is required same as followings.

Recommend to use high temperature soldering iron and apply $350\pm 10^{\circ}\text{C}$ temperature range, Soldering should be accomplished within 1-3 seconds at each terminal so as not to be overheated. Do not make a cavity at the surface on the PCB and wiring board (Opened cavity will influence to the sensitivity of ECM MIC). Optimal design for heat sink pad is same as below.

9.2 Soldering fixture



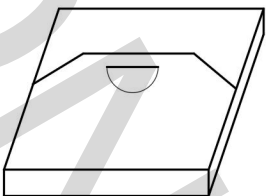
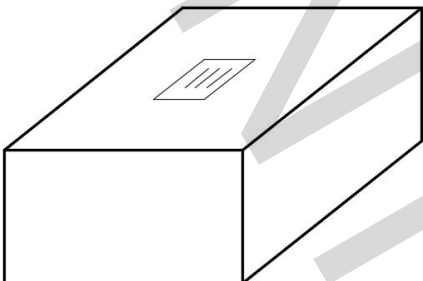
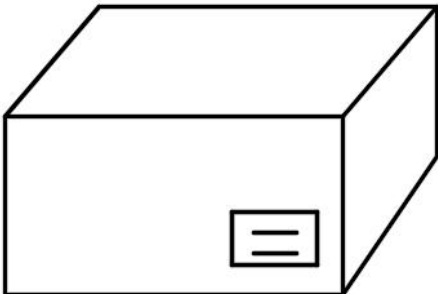
ECM eject hole.

Solder pad jig hole size: microphone diameter + 0.05mm.

Solder pad jig hole height: microphone height -0.2mm.

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10 The graphic of packing method as follows

	Drawing(Unit: mm)	Packing (PCS)	Qty (PCS)	Material
Packing		1*100	100	Paper
Middle bag		8*100	800	Paper
Carton		10*800	8000	Paper

Special note:

The above packaging method is universal packaging. If the actual shipment order quantity is less than the full box quantity or there is a slight surplus, the carton size and product packaging quantity will be adjusted. we won't notice again, if you have any questions, please contact our marketing department.